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C Moore

PATENT



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Rose M. Thiessen, Reg. No. 40,202

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Dear Sir:

In response to the Office Action mailed February 27, 2002 Applicants respectfully request that the Examiner enter the following amendments and consider the following remarks.

IN THE CLAIMS:

Please amend Claims 1-10 as follows:

1. (Amended) A method for forming a patterned hard mask layer in an organic polymer film for an interconnect structure in an integrated circuit, said method comprising:
- fluorinating a part of an organic polymer film, thereby forming a fluorinated part, said fluorinated part forming a first hard mask layer;
 - forming a patterned second hard mask layer on said film;
 - patterning said first hard mask layer using said patterned second hard mask layer as a mask, thereby forming a patterned first hard mask layer;